MMSD103T1G, SMMSD103T1G

High Voltage Switching Diode

Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	250	V
Peak Forward Current	١ _F	200	mA
Peak Forward Surge Current	I _{FM(surge)}	625	mA

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Forward Power Dissipation, FR-5 Board (Note 1) @ T _A = 25°C Derate above 25°C	P _F	400 3.2	mW mW/°C
Thermal Resistance, Junction-to-Case	$R_{ extsf{ heta}JL}$	174	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	492	°C/W
Junction and Storage Temperature Range	T _{J,} T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.



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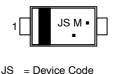
http://onsemi.com



SOD-123 CASE 425 STYLE 1



MARKING DIAGRAM



M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MMSD103T1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
SMMSD103T1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel

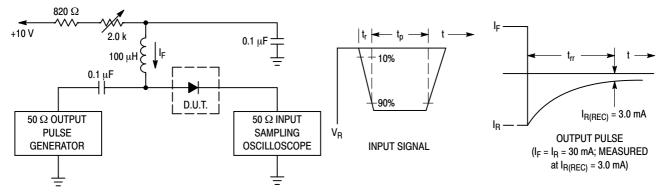
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

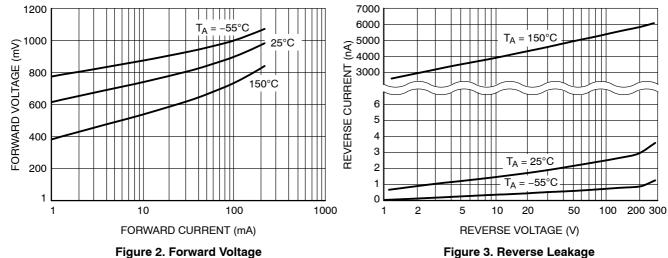
Characteristic	:	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	·				
Reverse Voltage Leakage Current $(V_R = 200 \text{ V})$ $(V_R = 200 \text{ V}, T_J = 150^{\circ}\text{C})$		I _R	-	1.0 100	μΑ
Reverse Breakdown Voltage (I _{BR} = 100 μA)		V _(BR)	250	_	V
Forward Voltage (I _F = 100 mA) (I _F = 200 mA)		V _F	- -	1000 1250	mV
Diode Capacitance (V _R = 0, f = 1.0 MHz)		C _D	_	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30 \text{ mA}, R_L = 100 \Omega$)		t _{rr}	_	50	ns



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 30 mA. 2. Input pulse is adjusted so I_{R(peak)} is equal to 30 mA. 3. t_p » t_{rr}



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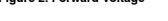
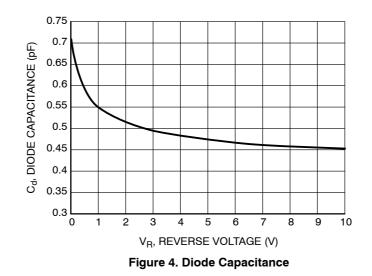
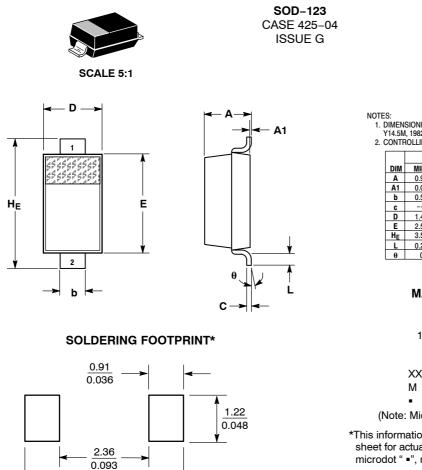


Figure 3. Reverse Leakage



MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON



SCALE 10:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

4.19

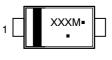
0.165

DATE 07 OCT 2009

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
C			0.15			0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		
θ	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

- = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

STYLE 1: PIN 1. CATHODE 2. ANODE

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